August 9, 2018
FUJI CORPORATION

Semiconductor equipment manufacturer Fasford Technology Co., Ltd. stock acquisition

Strengthening comprehensive proposals that include semiconductor related technology to build a business with further added value

Fuji Corporation (headquarters: Chiryu, Aichi, Japan; president & CEO: Nobuyuki Soga; hereafter called "Fuji") has entered into a contract on August 9th, 2018 to acquire all of the stock of semi-conductor manufacturing equipment manufacturer Fasford Technology Co., Ltd. (headquarters: Minami Alps City, Yamanashi, Japan; president & CEO: Hideto Fujiwara; hereafter called "Fasford") that are held by Advantage Partners together with other service provider funds for 21.8 billion Japanese Yen. By using the technological synergy of both companies, we plan on developing next generation technology for semi-conductor machines and surface mount technology machines and further improving quality. We will make innovative technology and products for manufacturing that will excite and inspire users while continuing to provide high value.

Background

Fuji is a robotic solutions company with their main business in providing electric component mounting robots that mount components at high-speed and high-accuracy, and these have garnered a top share in the world from their overwhelming performance. Fuji, as a world leading company, provides products that are a step ahead by focusing on high accuracy products and automating manufacturing work, as well as by grasping the constantly evolving needs of users.

Fuji has a goal for expanding into even more fields in the future, such as artificial Intelligence, self-driving cars, data centers, automotive, communication devices, and industrial devices. Thus, Fuji has decided to design, manufacture, and sell die bonding machines that are in the semiconductor market from the our new subsidiary company Fasford in order to provide strong next generation technology and solutions for complete production lines which incorporate both semiconductor processes and surface mount processes.

Fasford die bonder machines that are used to manufacture memory products such as DRAM and NAND have a world top share, and reflect the market needs in their timely product development. They have the development power to quickly release new machines in a timely manner. They have a lot of experience in delivering to OSAT (Outsourced Semiconductor Assembly and Test) and IDM (companies that design, manufacturer, and sell products under their own brand) and have a high presence in the major companies in the industry.

This will expand the robotic solutions business and further strengthen the position of Fuji as an industry leading company.

Fasford history

1. Name	Fasford Technology Co., Ltd.
2. Address	610-5 Shimoimasuwa, Minami Alps City, Yamanashi Pref., Japan
3. Representative (name and job title)	President & CEO: Hideto Fujiwara

4. Business type	The design, manufacture, sales, repair, and perform maintenance service of semiconductor manufacturing equipment.
5. Capital	100 million Japanese Yen (as of March 31, 2018)
6. Established	September 30, 2014
7. Production base	Minami Alps City
8. Employees	169 (as of end of May 2018)
9. Largest shareholders and stock ratios (As of March 31, 2018)	Japan Ireland Investment Partners-S Unlimited Company: 63.7% Advantage Partners, LLP. IV-S: 20.9% AP Cayman Partners II-S, L.P.: 12.4% Advantage Partners investment association 59: 2.9%

10. Operation results for the last three years

Accounting term:	March 2016	March 2017	March 2018
Sales	7,041 million Yen	10,474 million Yen	9,288 million Yen
Operating profit	577 million Yen	706 million Yen	733 million Yen
Net profit for the period	397 million Yen	490 million Yen	555 million Yen

11. Official website	http://www.fasford-tech.com/

Fasford products' main technology

(1) Low stress die picking technology: NMS (new technique) reduces additional bending stress on thin dies when peeling from the dicing tape by raising the four corners of thin dies by a small amount.

(2) Parallel pickup technology: By designing an intermediate stage between pickup and bonding and by differentiating between the heads used for pickup and bonding, it is possible to prevent heat transfer to heads from having a detrimental effect on pickup.

(3) High accuracy bonding technology: Maintains high accuracy even after long periods of operation.

(4) Clean technology: Maintains a clean state by creating an air flow in the machine and removing dust on the stage when laminating wafers.

Future development

By linking the technology cultivated from electronic component mounting robots and the technology related to semi-conductors from Fasford, Fuji Group will straddle these two separated fields to establish a new field of business and focus on creating new products with a high value and strengthen integrated proposals from industrial robots and semiconductor equipment manufacturers.

Company profile

Company: FUJI CORPORATION
Representative: Nobuyuki Soga, President & CEO
Address: 19 Chausuyama Yamamachi, Chiryu, Aichi, Japan 472-8686

Established: April 1959

Business divisions: Manufacturing and sales of electronic component mounter robots and machine tools

Capital: 5,878 million Yen

URL: http://www.fuji.co.jp/

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